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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-38 (canceled).

Claim 29 (previously presented): A lid material for a lid which is to be fuse-bonded to a peripheral upper surface of a case having an open top and a housing space for an electronic component, the lid material comprising:

a core layer;

a nickel-based metal layer composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer; and

a brazing material layer press-bonded onto the nickel-based metal layer such that the total thickness of the core layer, the nickel-based metal layer, and the brazing material layer is reduced by a ratio of between about 30% to about 60%;

wherein the nickel-based metal layer has a maximum-to-minimum thickness ratio  $T1/T2$  of 1.4 to 15.

Claim 30 (previously presented): A lid material as set forth in claim 29, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 31 (previously presented): A lid material as set forth in claim 29, wherein the brazing material layer is composed of a soft brazing material having a melting point

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of not higher than 450°C.

Claim 32 (previously presented): A lid material as set forth in claim 30, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 33 (previously presented): A lid material as set forth in claim 31, wherein the soft brazing material is free from lead.

Claim 34 (previously presented): A lid material as set forth in claim 32, wherein the soft brazing material is free from lead.

Claim 35 (previously presented): A lid material as set forth in claim 29, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 36 (canceled).

Claim 37 (previously presented): An electronic component package comprising:  
a case having an open top and a housing space for an electronic component;  
and

a lid provided on the top of the case, the lid comprising a core layer, a nickel-based metal layer composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer, and a brazing material layer press-bonded onto the nickel-based metal layer such that the total thickness of the core layer, the nickel-based metal layer, and the brazing material layer is reduced by a ratio of between about 30% to about 60%, the nickel-based metal layer having a maximum-to-minimum thickness ratio  $T1/T2$  of 1.4 to 15;

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wherein the brazing material layer of the lid is fuse-bonded to a peripheral upper surface of the case.

Claim 38 (previously presented): An electronic component package as set forth in claim 37, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 39 (previously presented): An electronic component package as set forth in claim 37, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 40 (previously presented): An electronic component package as set forth in claim 38, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 41 (previously presented): An electronic component package as set forth in claim 39, wherein the soft brazing material is free from lead.

Claim 42 (previously presented): An electronic component package as set forth in claim 40, wherein the soft brazing material is free from lead.

Claim 43 (previously presented): An electronic component package as set forth in claim 37, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 44 (canceled).